

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3633	(spreader or sink or heatsink or slug or stiffener) same (die or ic or chip) same substrate same (package or packaging)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/25 10:38
L2	1639	(spreader or sink or heatsink or slug or stiffener) same (die or ic or chip) same substrate same (package or packaging) same semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/25 10:38
L3	928	(spreader or sink or heatsink or slug or stiffener) same (die or ic or chip) same substrate same (package or packaging) same semiconductor same surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/25 10:38
L4	959	(spreader or sink or heatsink or slug or stiffener) same (die or ic or chip) same substrate same (package or packaging) same semiconductor same (plane or surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/25 10:39
L5	419	(spreader or sink or heatsink or slug or stiffener) same (die or ic or chip) same substrate same (package or packaging) same semiconductor same (plane or surface) same (epoxy or resin or encapsulant or encapsulating or encapsulated or encapsulation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/25 10:48
L6	0	09/923834	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/25 10:45
L7	2	"6853070"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/25 10:45
L8	147	(spreader or sink or heatsink or slug or stiffener) same (die or ic or chip) same substrate same (package or packaging) same semiconductor same (plane or surface) same (epoxy or resin or encapsulant or encapsulating or encapsulated or encapsulation) same portion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/25 10:48

## EAST Search History

L9	147	(spreader or sink or heatsink or slug or stiffener) same (die or ic or chip) same substrate same (package or packaging) same semiconductor same (plane or planar or surface) same (epoxy or resin or encapsulant or encapsulating or encapsulated or encapsulation) same portion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/25 10:48
L10	50	((spreader or sink or heatsink or slug or stiffener) same (die or ic or chip) same substrate same (package or packaging) same semiconductor same (plane or planar or surface) same (epoxy or resin or encapsulant or encapsulating or encapsulated or encapsulation) same portion).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/25 10:50
L11	147	((spreader or sink or heatsink or slug or stiffener) same (die or ic or chip) same substrate same (package or packaging) same semiconductor same (plane or planar or surface) same (epoxy or resin or encapsulant or encapsulating or encapsulated or encapsulation) same portion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/25 10:50
L12	88	((spreader or sink or heatsink or slug or stiffener) same (die or ic or chip) same substrate same (package or packaging) same semiconductor same (plane or planar or surface) same (epoxy or resin or encapsulant or encapsulating or encapsulated or encapsulation) same portion) and (spreader or sink or heatsink or slug or stiffener).clm. and (spreader or sink or heatsink or slug or stiffener).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/25 10:51